

Customer No.: 31561
Application No.: 10/710,401
Docket NO.: 11571-US-PA

Amendment

IN THE CLAIMS:

Claim 1 (currently amended) A chip structure, at least comprising:

a chip, having at least a bonding pad and a transmission line on a chip surface, wherein the transmission line is coupled to the bonding pad; and

a passivation layer, covering the chip surface, wherein the passivation has an opening to expose the bonding pad, wherein a top-view profile~~cross-section~~ of the opening is composed of~~includes~~ a straight line and an arc connecting to two ends of the straight line and the arc is a segment of a circle or an ellipse, and the straight line is adjacent~~near~~ to a connection terminal between the transmission line and the bonding pad.

Claim 2. (original) The chip structure of claim 1, wherein a length of the straight line is less than or equal to a radius of the arc.

Claim 3. (original) The chip structure of claim 1, wherein a length of the straight line is between a radius of the arc and a diameter of the arc.

Claim 4. (original) The chip structure of claim 1, wherein the passivation layer includes an organic passivation layer.

Claim 5. (original) The chip structure of claim 1, wherein the passivation layer includes an inorganic passivation layer.

Claim 6. (currently amended) A chip structure, at least comprising:

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a chip, having at least a bonding pad and a transmission line coupled to the bonding pad, wherein the bonding pad and the transmission line are on a chip surface; and

a passivation layer, covering the chip surface, wherein the passivation has an opening to expose the bonding pad, wherein a top-view profile~~cross-section~~ of the opening includes a curving line and an arc connecting to two ends of the curving line and the arc is a segment of a circle or an ellipse, wherein the curving line is concave to the arc and adjacent~~near~~ to a connection terminal between the transmission line and the bonding pad.

Claim 7. (currently amended) The chip structure of claim 6, wherein each point of the curving line has a ~~substantially equal~~ distance to the connection terminal between the transmission line and the bonding pad.

Claim 8. (original) The chip structure of claim 6, wherein a curvature of the curving line is less than or equal to a curvature of the arc.

Claim 9. (original) The chip structure of claim 6, wherein a curvature of the curving line is greater than or equal to a curvature of the arc.

Claim 10. (original) The chip structure of claim 6, wherein the passivation layer includes an organic passivation layer.

Claim 11. (original) The chip structure of claim 6, wherein the passivation layer includes an inorganic passivation layer.